

## **I403-VB Datasheet**

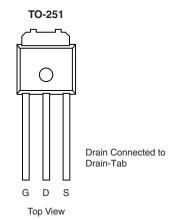
# P-Channel 30 V (D-S) MOSFET

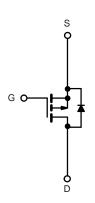
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS}(V)$ $R_{DS(on)}(\Omega)$			
- 30	$0.008 \text{ at V}_{GS} = -10 \text{ V}$	-70		
	0.011 at V <sub>GS</sub> = - 4.5 V	-60		

#### **FEATURES**

• Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)							
Parameter			Limit	Unit			
Gate-Source Voltage	$V_{GS}$	± 20	V				
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	- 70 <sup>a</sup>				
	T <sub>C</sub> = 125 °C		- 56				
Pulsed Drain Current	I <sub>DM</sub>	- 240	Α				
Avalanche Current	I <sub>AR</sub>	- 60					
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	180	mJ			
Danier Biasinstina	T <sub>C</sub> = 25 °C (TO-220AB and TO-263)	Б	187 <sup>d</sup>	W			
Power Dissipation	T <sub>A</sub> = 25 °C (TO-263) <sup>c</sup>	$P_{D}$	3.75				
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>sta</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) <sup>c</sup>	ь	40	°C/W		
Junction-to-Ambient	Free Air (TO-220AB)	R <sub>thJA</sub>	62.5			
Junction-to-Case		R <sub>thJC</sub>	0.8			

#### Notes:

- a. Package limited.
- b. Duty cycle  $\leq$  1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			- 3 V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1		- 3		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			- 50	μΑ	
		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			- 250	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 120			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.008		Ω	
Drain-Source On-State Resistance <sup>a</sup>	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 125 °C		0.010			
Diani-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 175 °C		0.011			
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.011			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 75 A	20			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			7000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		1265			
Reversen Transfer Capacitance	C <sub>rss</sub>			515			
Total Gate Charge <sup>c</sup>	$Q_g$			160	240		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -75 \text{ A}$		32		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			30			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			25	40		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 0.2 \Omega$		225	360	20	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong$ - 75 A, $V_{GEN}$ = - 10 V, $R_g$ = 2.5 $\Omega$		150	240	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	]		210	340		
Source-Drain Diode Ratings and Cha	racteristics <sup>b</sup>	(T <sub>C</sub> = 25 °C)					
Continuous Current	Is				- 80	۸	
Pulsed Current	I <sub>SM</sub>				- 240	Α	
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = -75 A, V <sub>GS</sub> = 0 V		- 1.2	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			55	100	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = - 75 A, dl/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	1		0.07	0.25	μC	

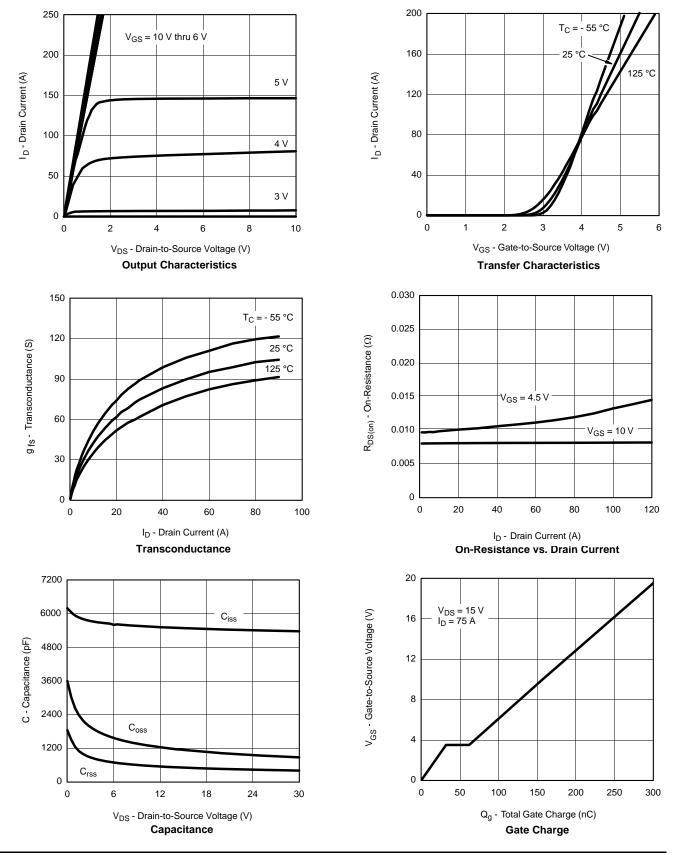
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

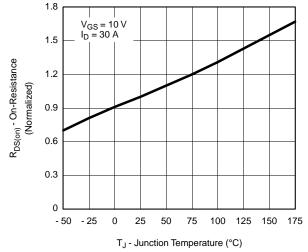


#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

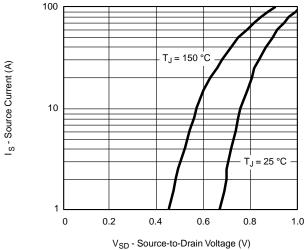




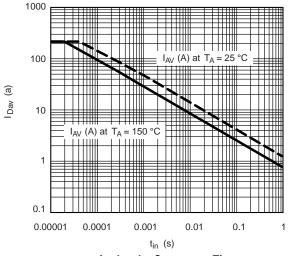
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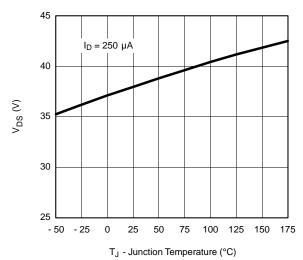
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



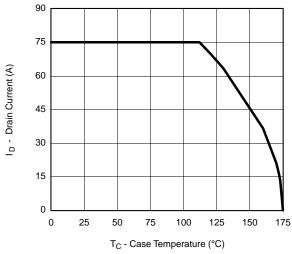
Avalanche Current vs. Time

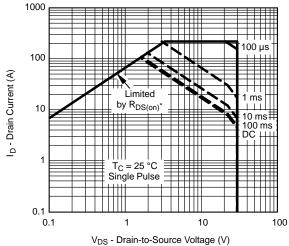


**Drain Source Breakdown** vs. Junction Temperature



#### THERMAL RATINGS



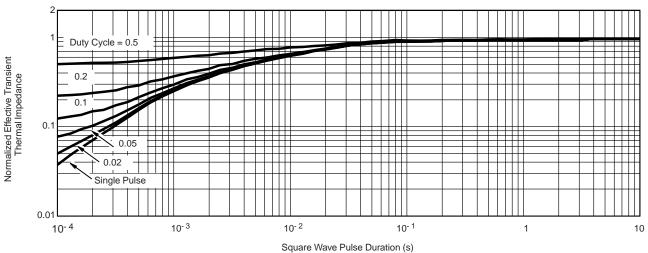


Maximum Avalanche and Drain Current vs. Case Temperature

 $V_{DS}$  - Drain-to-Source Voltage (V)

\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

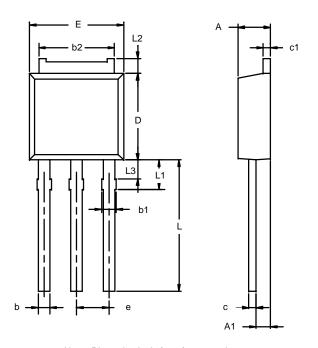
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



### TO-251AA



	MILLIMETERS INCI			HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
с1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
E	6.48	6.73	0.255	0.265
е	2.28 BSC		0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060



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